

FileViewEditToolsWindowHelp

Drafts

BRS:
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Pending

Active

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L2: (86) 0 2003/0104654 2002/0027273 36,468 394,844 402,638

L3: (86) 0 2003/0104654 2002/0027273 36,468 394,844 402,638

L4: (21) 0 2003/0104654 2002/0027273 394,844 402,638

L1: (50) 5,252,857 0

L5: (504) cavity near 4 defin 4 near 6 (lead lead frame)

L6: (2370863) (encapsula 3 encapsulation mold 3 resin)

L7: (132) 5 with 6

(2251450) (encapsula 3 encapsulation mold 3 resin)

(14073) stack 4 near 2 (microchip micro adj chip chip integrated adj circuit die ic - sem

(2460392) (offset stagger 3 shift 3 zigzag 4 align 4 near 2 angle pitch oblique 4 inclin

(12434) (lead frame lead adj frame) 0

(1218719) (lead frame lead adj frame lead)

(6841) (offset stagger 3 shift 3 zigzag 4 align 4 near 2 angle pitch oblique 4 inclin 4

(78) (lead frame lead adj frame) 0

(444) (lead frame lead adj frame) 0

(18011) (offset stagger 3 shift 3 zigzag 4 align 4 near 2 angle pitch oblique 4 inclin 4

(241) (lead frame lead adj frame) 0

(888) (lead frame lead adj frame) 0

(88) (lead frame lead adj frame) 0

DBs:USPAT;US POPUB;EPQ;JPG;DERWENT;IBM;TDB

Default operator:GR

5 with 6

Sept 2003

DBS:USPAT;US POPUB;EPQ;JPG;DERWENT;IBM;TDB

Default operator:GR

5 with 6

	U	Inventor	Document ID	Issue D	Pa	Title	Current D	Current X Ref	Retrieval Cl	S	C	P	Z	J	W	Image Doc	D	P
1	<input type="checkbox"/>	Hueng, Chien Pi	US 200200272	200203	12	Semiconductor package and fabricating method there	257/678	257/E23,046		R	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 200200272	<input type="checkbox"/>	
2	<input type="checkbox"/>		JP 05175398 A	199307	3	Resin-sealed semiconductor device prodn. - comprises				R	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	JP 05175398	<input type="checkbox"/>	
3	<input type="checkbox"/>		JP 60111432 A	198508	4	Resin sealing die for semiconductor device - comprises				R	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	JP 60111432	<input type="checkbox"/>	
4	<input type="checkbox"/>		JP 60109238 A	198508	4	Resin moulding appts. for sealing semiconductor devic				R	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	JP 60109238	<input type="checkbox"/>	
5	<input type="checkbox"/>		JP 53078849 A	197807	3	Metal mould for thermoplastic resin - used for holding				R	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	JP 53078849	<input type="checkbox"/>	
6	<input type="checkbox"/>	ARAI, T et al.	US 4751611 A	198808	4	Package structure for semiconductor element e.g. IC				R	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 4751611	<input type="checkbox"/>	
7	<input type="checkbox"/>	Adachi, Masaki	US 6091139 A	200007	13	Semiconductor device	257/680	257/666		R	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6091139	<input type="checkbox"/>	
8	<input type="checkbox"/>	Alfaro, Rafael C	US 5458716 A	199510	8	Methods for manufacturing a thermally enhanced mold	156/245	156/292		R	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 5458716	<input type="checkbox"/>	

Ready

16.96